The stress analysis of the adhesive's influences on bonded substrate

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ABSTRACT

In this investigation, the adherend of the adhesively bonded joint is modeled as a 1-D beam. Based on the mechanics of material, the analytical solutions of the shear and peel stresses in the adhesive are obtained first, and by considering the force-balance of the system, the strain of the adherend can be obtained. Then, the analytical solutions of adhesive 's stress and adherend 's strain are compared with the 2-D finite element solutions (numerical solution). The analysis of bonded joints involves three different types of applying loadings: axial force, moment, and both axial force and moment. The distribution of the adhesive 's stresses and the strain of adherend are discussed. The parameters which may effect the distribution of the adhesive 's stresses and the adherend 's strain, including mechanical properties, geometries of adhesive/adherend, and the length of bonded joints are studied. Finally, an experimental tensile test with axial force on bonded joints is set to validate the analytical solutions of the adherend 's strain distributions

Keywords: adhesively bonded joint, beam theory, shear stress, peel stress, strain, parameters study

Table of Contents

授權書	中文摘要		iv 英文摘要	v 誌
謝	vi 目錄	vii 圖	目錄	ix 表目
錄	xiii 第一章 緒論	1	1.1 前言	1 1.2 研
究動機	2 1.3 文獻回顧	4	1.4 研究內容與方法	5 第
二章 黏著件力學分析.	7 2.1 膠/	層應力控制方程式	8 2.2 邊界條	
件	17 2.3 基板受力分析	20 :	2.4 基板應變分析	24 2.5
實例分析與驗證	26 2.5.1 負載	遺條件Ⅰ:軸向力	27 2.5.2 負載條何	牛II:彎
矩	.31 2.5.3 負載條件III:軸向力	り與彎矩34	4 第三章 參數分析	37
3.1 膠層參數	37 3.1.1 相同	引膠層材料,不同膠層厚原	度 38 3.1.2 相	同膠層厚度,不同膠
層材料4	45 3.2 基板參數	53 3.2.1 上、	下基板相同材質而厚度不	司 53
3.2.2 上、下基板相同/	厚度而不同材質	61 3.3 黏著長度	65 第四章	宣實驗與比
較	68 4.1 實驗方法與設計	68 4.	1.1 基板材料之楊係係數	68
4.1.2 黏著件之設計與	製作71 4.2	2 實驗與驗證	76 4.2.1 實驗類	R
設	76 4.2.2 實驗結果與討詞	侖 79	第五章 結論	85 參考
文獻	88 附錄 基板相同	材料與厚度時之力學分析	f 92	

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